

REMARKS

By this Supplemental Amendment, a previously overlooked occurrence of
“through hall” in Claim 7 has been change to - - through hole - - .

Entry of this Supplemental Amendment is requested.

Respectfully submitted,

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By:


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ATTACHMENT "A"

Additions/Deletions to Claim 7:

7. (Twice amended) A method of manufacturing a semiconductor device with a semiconductor element fixed to a semiconductor package, comprising the steps of:

preparing said semiconductor package structured by providing a substrate for mounting said semiconductor element thereon to fix said semiconductor element to one side thereof and a connecting pattern provided on the other side of said substrate and by forming a through hole from the one side to the other side of said substrate;

fixing a surface where the element is formed of said semiconductor element on the one side of said substrate of said semiconductor package such that an electrode of said semiconductor element is within said through hole; electrically connecting said connecting pattern and said electrode of said semiconductor element via wires through said through hole; and sealing said through ~~hail~~ hole and said wires with resin.